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xecution Date(s): in parentheses after inventor name	Street Address:
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Nature of Conveyance:	Tokyo 108-0075
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11/657,934	
Additional numbers attache	
. Name and address to whom correspondence concerning document should be mailed:	6. Total number of applications and 1 patents involved:
Name: Bruno Polito	
LERNER, DAVID, LITTENBERG,	7. Total fee (37 CFR 1.21(h & 3.41) \$ 40.00
KRUMHOLZ & MENTLIK, LLP	
	Authorized to be charged by credit card
Internal Address: Atty, Dkt.:	
	Authorized to be of arged to deposit account
Street Address: 600 South Avenue West	
	Enclosed
	None required (go 'ernment interest not affecting title
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Phone Number: (908) 518-637486	b. Deposit Account Numter 12-1095
Fax Number: (908) 654-0415 Email Address: dsmid@ldlkm.com	Authorized User Name Bruno Polito
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9. Signature:	October 13, 2008
Signature	Total number of pages including cover 3
Bruno Polito - 38,580 Name of Person Signing	sheet, atta- hments, and documents:
Name of reson oighing	

## PATENT REEL: 021671 FRAME: 0037

SO7P0122US00 SONYJP 3.0-1302 Docket Number:

## ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in EXPOSURE CONICL APPARATUS AND IMAGE PICKUP APPARATUS

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35 Kitashinagawa 6-Chome, Shinagawa-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all int trest in, to and under said invention, said application disclosing the invention and in, to and under any Letters. Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereo<sup>2</sup>, and in and to any and all Letters patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Froperty, Inter-American Convention rights and/or convention rights under the International Convention for the Protection of Industrial Froperty, Inter-American Convention adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents to issue the patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title ard interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGN E thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in fortign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: <u>11/657,934</u>, Filing Date: <u>January 25, 2007</u>

This assignment executed on the dates indicated below.

Ruihua XIAO

Name of first or sole inventor

Tokyo, Japan

Residence of first or sole inventor

Signature of first or sole inventor

Execution date of U.S. Patent Application

PATENT REEL: 021671 FRAME: 0038

S07P0122US00

## Akira SHIGA

Name of second inventor

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Tokyo, Japan

Residence of second inventor

Signature of second inventor

Name of third inventor

Residence of third inventor

Signature of third inventor

Name of fourth inventor

Residence of fourth inventor

Signature of fourth inventor

Name of fifth inventor

Residence of fifth inventor

Signature of fifth inventor

Date of this assignment

REEL: 021671 FRAME: 0039

Execution date of U.S. Patent Application

Jainwary 16, 2007 Date of this assignment

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**RECORDED: 10/13/2008**